

**256K x 8 LOW POWER and LOW Vcc
CMOS STATIC RAM**

**ADVANCE INFORMATION
FEBRUARY 1999**

FEATURES

- Access times of 70 ns, 85 ns, and 100 ns
- Low active power: 126 mW (max, L, LL)
- Low standby power: 36 μ W (max, L) and 7.2 μ W (max, LL) CMOS standby
- Low data retention voltage: 2V (min.)
- Available in Low Power (-L) and Ultra-Low Power (-LL)
- Output Enable (\overline{OE}) and two Chip Enable ($\overline{CE1}$ and $CE2$) inputs for ease in applications
- TTL compatible inputs and outputs
- Single 2.7V to 3.6V power supply

DESCRIPTION

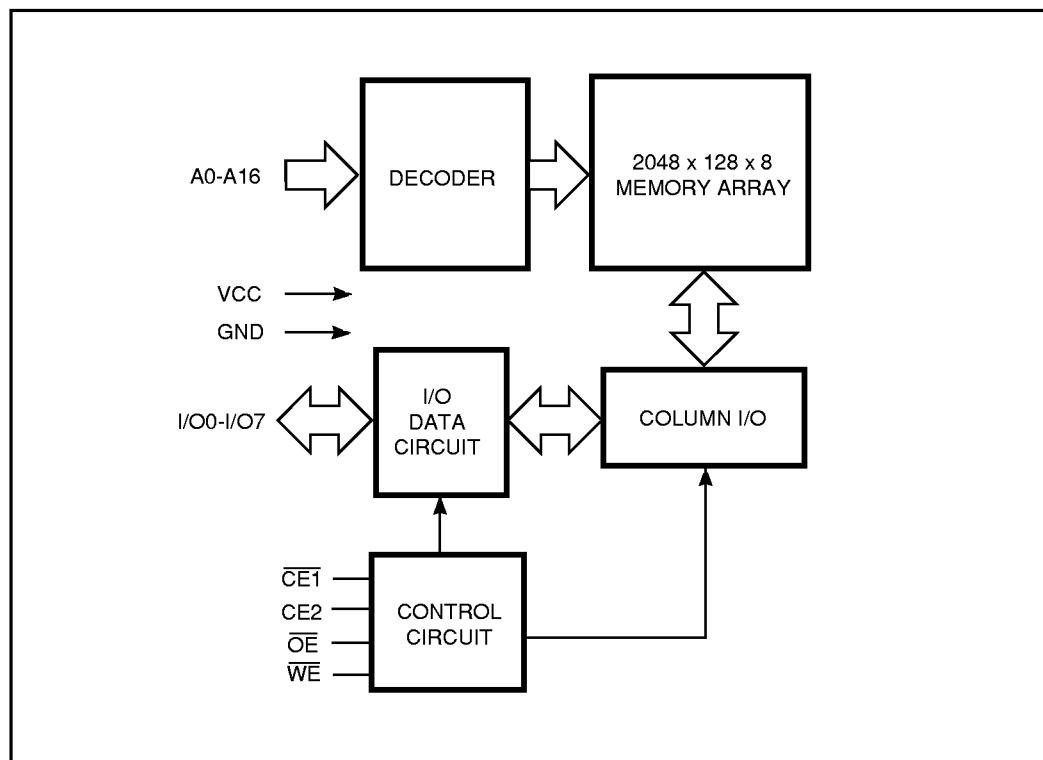
The ISSI IS62LV2568L and IS62LV2568LL are low power and low Vcc, 262,144-word by 8-bit CMOS static RAMs. They are fabricated using ISSI's high-performance CMOS technology. This highly reliable process coupled with innovative circuit design techniques, yields higher performance and low power consumption devices.

When $\overline{CE1}$ is HIGH or $CE2$ is LOW (deselected), the device assumes a standby mode at which the power dissipation can be reduced by using CMOS input levels.

Easy memory expansion is provided by using two Chip Enable inputs, $\overline{CE1}$ and $CE2$. The active LOW Write Enable (\overline{WE}) controls both writing and reading of the memory.

The IS62LV2568L and IS62LV2568LL are available in 32-pin TSOP (Type I) and STSOP (Type II).

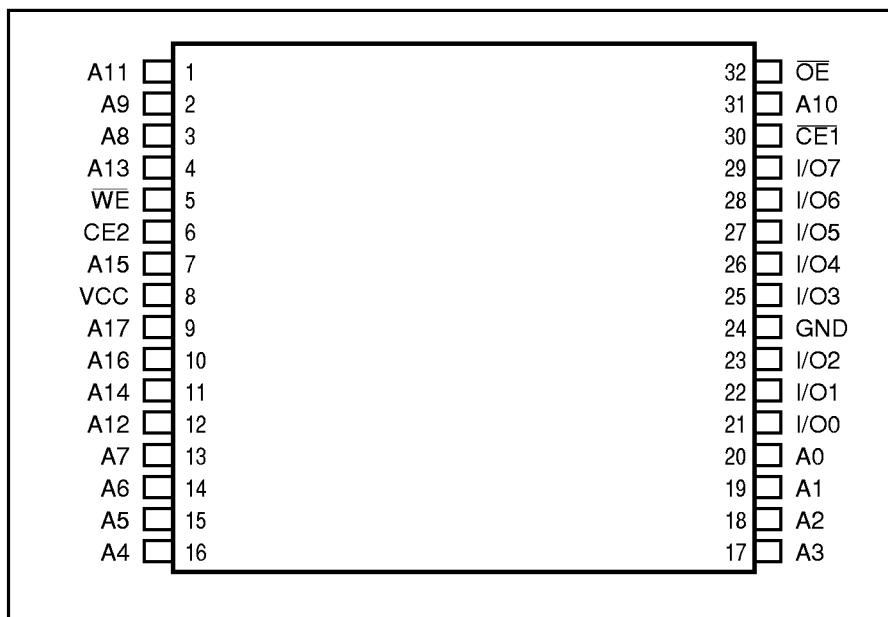
FUNCTIONAL BLOCK DIAGRAM



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PIN CONFIGURATION

32-Pin TSOP (Type I), STSOP (Type I)

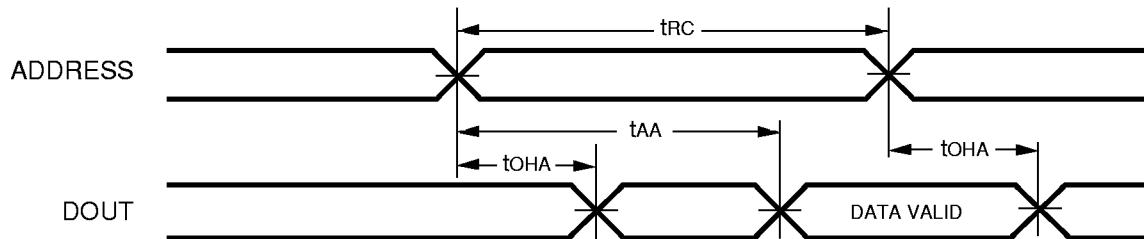
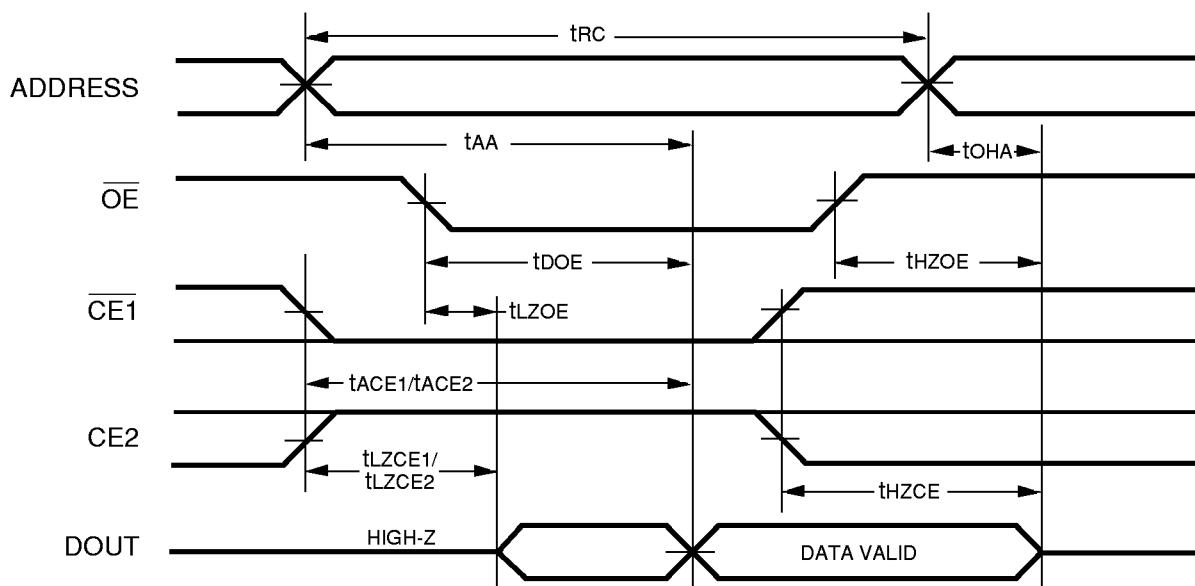
**PIN DESCRIPTIONS**

A0-A17	Address Inputs
CE1	Chip Enable 1 Input
CE2	Chip Enable 2 Input
OE	Output Enable Input
WE	Write Enable Input
I/O0-I/O7	Input/Output
NC	No Connection
Vcc	Power
GND	Ground

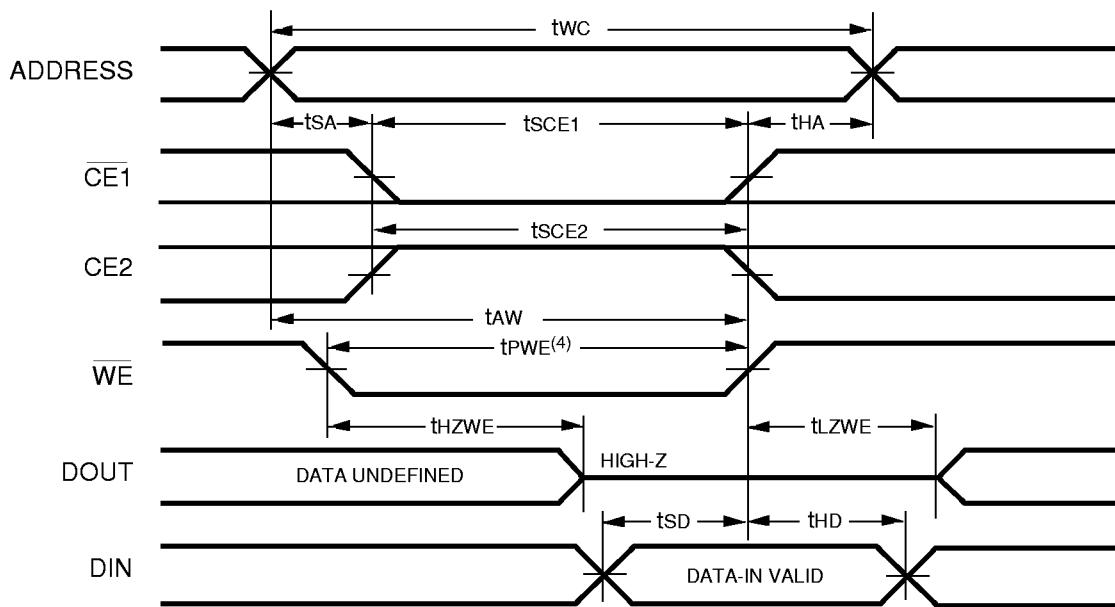
OPERATING RANGE

Range	Ambient Temperature	Vcc
Commercial	0°C to +70°C	2.7V to 3.6V
Industrial	-40°C to +85°C	2.7V to 3.6V

AC WAVEFORMS

READ CYCLE NO. 1^(1,2)READ CYCLE NO. 2^(1,3)**Notes:**

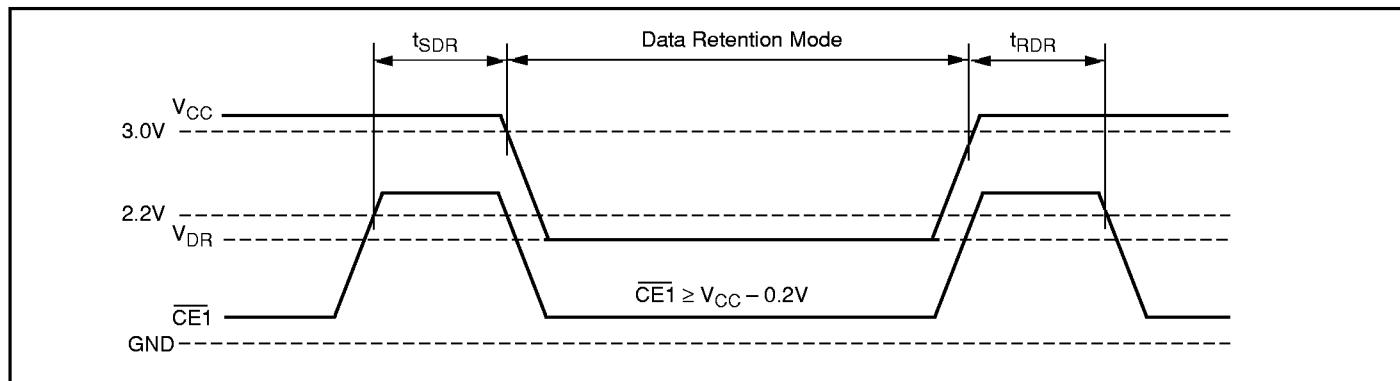
1. WE is HIGH for a Read Cycle.
2. The device is continuously selected. \overline{OE} , $\overline{CE1} = V_{IL}$, $CE2 = V_{IH}$.
3. Address is valid prior to or coincident with $CE1$ LOW and $CE2$ HIGH transitions.

WRITE CYCLE NO. 2 ($\overline{CE1}$, $CE2$ Controlled)^(1,2)**Notes:**

1. The internal write time is defined by the overlap of $\overline{CE1}$ LOW, $CE2$ HIGH and \overline{WE} LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the Write.
2. I/O will assume the High-Z state if $\overline{OE} = V_{IH}$.

DATA RETENTION SWITCHING CHARACTERISTICS

Symbol	Parameter	Test Condition		Min.	Max.	Unit
V _{DR}	V _{CC} for Data Retention	See Data Retention Waveform		2.0	3.6	V
I _{DR}	Data Retention Current	V _{CC} = 2.0V, $\overline{CE1} \geq V_{CC} - 0.2V$	Com. (-L) Com. (-LL) Ind. (-L) Ind. (-LL)	— — — —	10 2 15 5	μA
t _{SDR}	Data Retention Setup Time	See Data Retention Waveform		0	—	ns
t _{RDR}	Recovery Time	See Data Retention Waveform		t _{RC}	—	ns

DATA RETENTION WAVEFORM ($\overline{CE1}$ Controlled)**DATA RETENTION WAVEFORM (CE2 Controlled)**